

Keynote

Tuesday, March 17, 9:10 a.m. - 10:10 a.m.

Innovations in Thermal Management of Electronic Devices



Presenter: Andy Delano
Microsoft

Andy plans to highlight innovations from across the industry and over the last ~ 5-7 years and also talk about what he has found to be effective techniques for innovating over the course of his career.

Andy Delano leads the Microsoft Surface team's thermal architectural and technology efforts. Prior to joining Microsoft in 2012, Andy managed the thermal R&D team within Honeywell's electronic materials division developing and launching highly successful products for the electronics packaging industry. Andy started his career in 1998 as a thermal engineer at Hewlett-Packard designing server and workstation thermal systems. While at HP, Andy was also an adjunct professor at CU and taught heat transfer, thermodynamics, and thermal systems design between 1999 and 2005.

Prior to his career, Andy obtained his Ph.D. in mechanical engineering from Georgia tech in 1998, and his thesis was on a single pressure absorption refrigerator originally patented by Albert Einstein. During the first part of his graduate studies, Andy also worked on the design and production of the 1996 Olympic Torch and spent 6 weeks traveling with the torch relay.